

Amendments to the Claims:

1. (Currently Amended) An implant comprising
a sensor device being fixedly connected to a first end of a longitudinal carrier;
an inductive coil connected to the sensor device via electrical connection lines
that are arranged on the longitudinal carrier; and
a covering encapsulating the sensor device, the carrier with the connection
lines and the coil;
wherein the carrier has a sufficient rigidity such that the sensor device is
adapted to be guided by the carrier during implantation to a target position and held
in position at the target position, and that the covering part has means for providing a
subcutaneous fastening, ~~the carrier is flat with a rectangular cross section, the~~
carrier is in a substantially planar shape and is bendable from said planar shape to a
shape wherein the carrier is arranged at an angle from 60° to 120° relative to the
plane in which the coil windings of the inductive coil are arranged.
2. (Canceled)
3. (Previously Presented) The implant according to claim 1, wherein
there are provided two connection lines between the coil and the sensor
device.
4. (Previously Presented) The implant according to claim 1, wherein
the carrier is flat .
5. (Previously Presented) The implant according to claim 1 , further comprising
a stiffening foil being provided in the covering part.
6. (Previously Presented) The implant according to claim 5, wherein
the carrier is formed as at least one of a rod and a foil.

7. (Canceled)
8. (Previously Presented) The implant according to claim 1, wherein
a frame is fastened at the first end of the carrier , the sensor device
positively fits within the frame.
9. (Previously Presented) The implant according to claim 8, wherein
the frame is formed one piece with the carrier .
10. (Previously Presented) The implant according to claim 1, wherein
the carrier is formed as a common carrier for the electrical connection lines
and the coil windings.
11. (Previously Presented) The implant according to claim 1, wherein
the sensor device comprises at least one pressure sensor.
12. (Previously Presented) The implant according to claim 1, wherein
the covering part encapsulating the coil is adapted to be arranged in an
interior of the brain.
13. (Previously Presented) The implant according to claim 12, wherein
the encapsulating material of the covering part covering the sensor device is
formed as a pressure transmitting medium.
14. (Previously Presented) The implant according to claim 1,
wherein the sensor device is adapted to be positioned for at least one of an
intraparenchymal and a intraventricular pressure measurement.
15. (Previously Presented) An implant according to claim 2, wherein the angle is
from 60° to 120°.

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16. (Previously Presented) An implant according to claim 12, wherein the covering part encapsulating the coil is adapted to be arranged in the epidural.

17. (Canceled)

18. (New) An implant according to claim 13, wherein the carrier is bendable substantially about a line adjacent to said inductive coil.